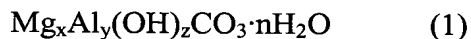


IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (original): An epoxy resin composition for encapsulating semiconductors comprising (A) an epoxy resin, (B) a phenol resin, (C) an inorganic filler, (D) a curing accelerator, (E) a glycerol tri-fatty acid ester produced by dehydration condensation reaction of glycerol and a saturated fatty acid with a carbon atom content of 24-36, and (F) a hydrotalcite compound.

Claim 2 (original): The epoxy resin composition for encapsulating semiconductors according to claim 1, wherein the hydrotalcite compound is a compound shown by the following formula (1) and/or its sintered material,



wherein x, y, z, and n are positive numbers.

Claim 3 (original): The epoxy resin composition for encapsulating semiconductors according to claim 2, wherein the hydrotalcite compound is a hydrotalcite of the above formula (1) in which $0.15 \leq (y/x+y) \leq 0.35$, $1.8 \leq (z/x+y) \leq 2.5$, and $0 \leq n \leq 5$ and/or its sintered material.

Claim 4 (original): The epoxy resin composition for encapsulating semiconductors according to claim 1, wherein the hydrotalcite compound is a compound shown by the formula $\text{Mg}_6\text{Al}_2(\text{OH})_{16}\text{CO}_3 \cdot 4\text{H}_2\text{O}$.

Claim 5 (previously presented): A semiconductor device comprising a semiconductor element encapsulated using the epoxy resin composition according to claim 1.

Claim 6 (new): A semiconductor device comprising a semiconductor element encapsulated using the epoxy resin composition according to claim 2.

Claim 7 (new): A semiconductor device comprising a semiconductor element encapsulated using the epoxy resin composition according to claim 3.

Claim 8 (new): A semiconductor device comprising a semiconductor element encapsulated using the epoxy resin composition according to claim 4.